



PATENT
Attorney Docket No. UM-04985

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CLEAN VERSION OF REWRITTEN OR ADDED CLAIMS
PURSUANT TO 37 CFR § 1.21 (c)(1)(i)

Please amend the following claims.

- Sub F1
1. (Amended) A device comprising:
- i) a housing comprised of a substrate, said substrate selected from the group consisting of silicon, glass and quartz;
 - ii) a fluid transport channel in said substrate, said channel connecting to a reaction region; and
 - iii) a series of heating elements arrayed along said fluid transport channel, wherein said series of heating elements are configured so as to provide differential heating.
- DX

- Sub F3
8. (Amended) A system comprising:
- i) a microdroplet;
 - ii) first and second microdroplet transport channels in a substrate, said channels connecting to a reaction region, said substrate selected from the group consisting of silicon, glass and quartz; and
 - iii) a series of heating elements arrayed along said first and second transport channels, wherein said series of heating elements are configured so as to provide differential heating of said microdroplet by said heating elements.
- DX

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[Please add the following claims.]

- Sub F4
13. (New) A device comprising:
- i) a first housing portion;
 - ii) a fluid transport channel in said first housing portion, said channel connecting to a reaction region;
- DX

Sub FH

- iii) a second housing portion bonded to and aligned with said first housing portion thus creating an assembled housing; and
- iv) a series of heating elements in said assembled housing arrayed along said fluid transport channel, wherein said series of heating elements are configured so as to provide differential heating.

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Cont

14. (New) The device of Claim 13, wherein said heating elements are comprised of aluminum.
15. (New) The device of Claim 13, wherein said transport channel is treated with a hydrophilicity-enhancing compound.
16. (New) The device of Claim 13, wherein said transport channel comprises silicon.
17. (New) The device of Claim 16, wherein said transport channel further comprises a first silicon oxide layer, a silicon nitride layer, and a second silicon oxide layer.
18. (New) The device of Claim 13, further comprising a second microdroplet transport channel in said first housing.
19. (New) The device of Claim 13, further comprising a second series of heating elements arrayed along said second transport channel.
20. (New) The device of Claim 13, wherein said first and second transport channels are etched in said first housing.